

Title (en)

MULTI-CHEMISTRY PLATING SYSTEM

Title (de)

METALLABSCHIEDUNGSSYSTEM MIT MEHREREN CHEMISMEN

Title (fr)

SYSTEME DE GALVANISATION A CHIMIE MULTIPLE

Publication

EP 1694885 A4 20071219 (EN)

Application

EP 04760000 A 20040416

Priority

- US 2004012012 W 20040416
- US 46386003 P 20030418
- US 46397003 P 20030418
- US 46386103 P 20030418
- US 46395603 P 20030418
- US 46386203 P 20030418

Abstract (en)

[origin: WO2004094702A2] Embodiments of the invention generally provide an electrochemical plating system. The plating system includes a substrate loading station positioned in communication with a mainframe processing platform, at least one substrate plating cell positioned on the mainframe, at least one substrate bevel cleaning cell positioned on the mainframe, and a stacked substrate annealing station positioned in communication with at least one of the mainframe and the loading station, each chamber in the stacked substrate annealing station having a heating plate, a cooling plate, and a substrate transfer robot therein.

IPC 8 full level

C25D 7/12 (2006.01); **B08B 3/02** (2006.01); **C25D 5/00** (2006.01); **C25D 17/00** (2006.01); **C25D 17/02** (2006.01); **C25D 19/00** (2006.01); **C25D 21/00** (2006.01); **C25D 21/08** (2006.01); **H01L 21/00** (2006.01); **H01L 21/68** (2006.01); **H01L 21/687** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP)

B08B 3/02 (2013.01); **C25D 5/003** (2013.01); **C25D 7/123** (2013.01); **C25D 17/001** (2013.01); **C25D 17/002** (2013.01); **C25D 21/02** (2013.01); **C25D 21/08** (2013.01); **H01L 21/67028** (2013.01); **H01L 21/67034** (2013.01); **H01L 21/67051** (2013.01); **H01L 21/67109** (2013.01); **H01L 21/67167** (2013.01); **H01L 21/6719** (2013.01); **H01L 21/67196** (2013.01); **H01L 21/6723** (2013.01); **H01L 21/68** (2013.01); **H01L 21/68707** (2013.01); **H01L 21/6838** (2013.01)

Citation (search report)

- [E] WO 2004075266 A2 20040902 - APPLIED MATERIALS INC [US], et al
- [E] WO 2004057060 A2 20040708 - APPLIED MATERIALS INC [US]
- [X] US 2003020928 A1 20030130 - RITZDORF THOMAS L [US], et al
- See references of WO 2004094702A2

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2004094702 A2 20041104; WO 2004094702 A3 20061130; WO 2004094702 A8 20051229; EP 1694885 A2 20060830;
EP 1694885 A4 20071219; JP 2007525591 A 20070906; TW 200502439 A 20050116; TW I265216 B 20061101

DOCDB simple family (application)

US 2004012012 W 20040416; EP 04760000 A 20040416; JP 2006513120 A 20040416; TW 93110691 A 20040416